

08/10/04

RELIABILITY REPORT FOR

## DS1848, Rev D1

# **Dallas Semiconductor**

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Prepared by:

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### **Conclusion:**

The following qualification successfully meets the quality and reliability standards required of all Dallas Semiconductor products and processes:

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In addition, Dallas Semiconductor's continuous reliability monitor program ensures that all outgoing product will continue to meet Maxim's quality and reliability standards. The current status of the reliability monitor program can be viewed at http://www.maxim-ic.com/TechSupport /dsreliability.html.

### **Device Description:**

A description of this device can be found in the product data sheet. You can find the product data sheet at http://dbserv.maxim-ic.com/l\_datasheet3.cfm.

### **Reliability Derating:**

The Arrhenius model will be used to determine the acceleration factor for failure mechanisms that are temperature accelerated.

AfT = exp((Ea/k)\*(1/Tu - 1/Ts)) = tu/ts AfT = Acceleration factor due to Temperature tu = Time at use temperature (e.g. 55°C) ts = Time at stress temperature (e.g. 125°C) k = Boltzmann's Constant (8.617 x 10-5 eV/°K) Tu = Temperature at Use (°K) Ts = Temperature at Stress (°K) Ea = Activation Energy (e.g. 0.7 ev)

The activation energy of the failure mechanism is derived from either internal studies or industry accepted standards, or activation energy of 0.7ev will be used whenever actual failure mechanisms or their activation energies are unknown. All deratings will be done from the stress ambient temperature to the use ambient temperature.

An exponential model will be used to determine the acceleration factor for failure mechanisms, which are voltage accelerated.

 $\begin{array}{l} AfV = \exp(B^*(Vs - Vu))\\ AfV = Acceleration factor due to Voltage\\ Vs = Stress Voltage (e.g. 7.0 volts)\\ Vu = Maximum Operating Voltage (e.g. 5.5 volts)\\ B = Constant related to failure mechanism type (e.g. 1.0, 2.4, 2.7, etc.) \end{array}$ 

The Constant, B, related to the failure mechanism is derived from either internal studies or industry accepted standards, or a B of 1.0 will be used whenever actual failure mechanisms or their B are unknown. All deratings will be done from the stress voltage to the maximum operating voltage. Failure rate data from the operating life test is reported using a Chi-Squared statistical model at the 60% or 90% confidence level (Cf).

The failure rate, Fr, is related to the acceleration during life test by:

Fr = X/(ts \* AfV \* AfT \* N \* 2)X = Chi-Sq statistical upper limit N = Life test sample size Failure Rates are reported in FITs (Failures in Time) or MTTF (Mean Time To Failure). The FIT rate is related to MTTF by:

MTTF = 1/Fr

NOTE: MTTF is frequently used interchangeably with MTBF.

The calculated failure rate for this device/process is:

FAILURE RATE:	MTTF (YRS): 54001	FITS: 2.1
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The parameters used to calculate this failure rate are as follows:

Cf: 60%	Ea: 0.7	B: 0	Tu: 25 °C	Vu: 5.5 Volts
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The reliability data follows. A the start of this data is the device information. The next section is the detailed reliability data for each stress. The reliability data section includes the latest data available.

#### **Device Information:**

Process:	E6W-2P2M,HPVt,E2,EPROGVt,TCZ ALOCOS:GOI
Passivation:	Passivation w/Nov TEOS Oxide-Nitride
Die Size:	98 x 100
Number of Transistors:	1
Interconnect:	Aluminum / 1% Silicon / 0.5% Copper
Gate Oxide Thickness:	150 Å

ELECTRICAL CHARACTERIZATION						
DESCRIPTION	DATE COD	DATE CODE CONDITION		DPOINT	QUANTITY	FAILS
ESD SENSITIVITY	0424	EOS/ESD S5.1 HBM 500 VOLTS	1	PUL'S	3	0
ESD SENSITIVITY	0424	EOS/ESD S5.1 HBM 1000 VOLTS	1	PUL'S	3	0
ESD SENSITIVITY	0424	EOS/ESD S5.1 HBM 2000 VOLTS	1	PUL'S	3	0
ESD SENSITIVITY	0424	EOS/ESD S5.1 HBM 4000 VOLTS	1	PUL'S	3	0
ESD SENSITIVITY	0424	EOS/ESD S5.1 HBM 8000 VOLTS	1	PUL'S	3	3
				To	tal:	3

OPERATING LIFE						
DESCRIPTION	DATE COD	E CONDITION	REA	DPOINT	QUANTITY	FAILS
HIGH TEMP OP LIFE	0335	125C, 5.5 VOLTS	100	) HRS	77	0
HIGH TEMP OP LIFE	0345	125C, 5.25 VOLTS	100	HRS	77	0
HIGH TEMP OP LIFE	0405	125C, 5.5 VOLTS	100	HRS	45	0
HIGH TEMP OP LIFE	0416	125C, 5.5 VOLTS	100	) HRS	77	0
HIGH TEMP OP LIFE	0417	125C, 5.5 VOLTS	100	) HRS	77	0
HIGH TEMP OP LIFE	0418	125C, 5.5 VOLTS	100	) HRS	77	0
HIGH TEMP OP LIFE	0418	125C, 5.5 VOLTS	192	HRS	77	0
HIGH TEMP OP LIFE	0424	125C, 5.5 VOLTS	192	HRS	77	0
				То	tal:	0

#### W/E ENDURANCE AND DATA RET'N DESCRIPTION DATE CODE CONDITION

DESCRIPTION	DATE CODE	CONDITION	READ	POINT	QUANTITY	FAILS
WRITE CYCLE STRESS STORAGE LIFE	0335	85 C, 5.5 VOLTS 150C	25 1000	KCYS HRS	77 76	0 0
WRITE CYCLE STRESS STORAGE LIFE	0401	25 C, 5.0 VOLTS 250C	50 4	KCYS HRS	76 76	0 0
WRITE CYCLE STRESS STORAGE LIFE	0416	70 C, 5.5 VOLTS 150C	30 1000	KCYS HRS	77 77	0 0
WRITE CYCLE STRESS STORAGE LIFE	0418	55 C, 5.5 VOLTS 150C	30 1000	KCYS HRS	77 77	0 0
WRITE CYCLE STRESS STORAGE LIFE	0418	70 C, 5.5 VOLTS 150C	30 96	KCYS HRS	77 77	0 0
WRITE CYCLE STRESS STORAGE LIFE	0424	85 C, 5.5 VOLTS 150C	30 96	KCYS HRS Tot	77 77	0 0 <b>0</b>
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FAILURE RATE:

MTTF (YRS): 54001 FITS: 2.1